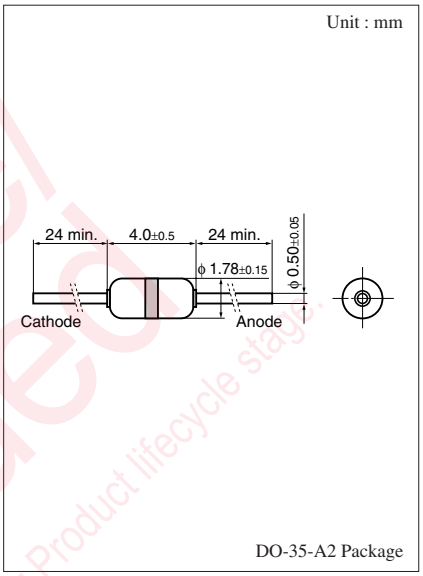
MA2B001

Silicon planar type trigger device

Thyristor TRIAC trigger circuit



■ Features

- Satisfactory symmetry of breakover voltage V_{BO}
- Large output voltage V_O and small breakover current I_{BO}

■ Absolute Maximum Ratings $T_a = 25°C$

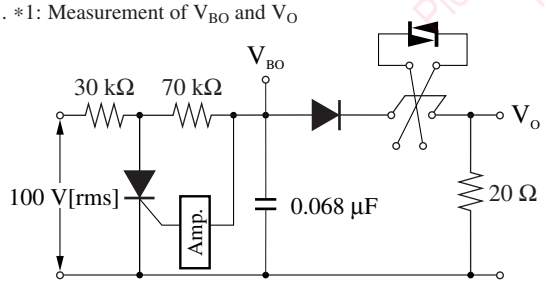
Parameter	Symbol	Rating	Unit
Power dissipation (Average)	$P_{D(AV)}$	150	mW
Peak current *1	I_P	2.0	A
Operating ambient temperature *2	T_{opr}	100	°C
Storage temperature	T_{stg}	−55 to +125	°C

Note) ∗1: $T_a < 50°C$, t = 10 µs, repetitive frequency 60 Hz
∗2: Maximum ambient temperature during operation

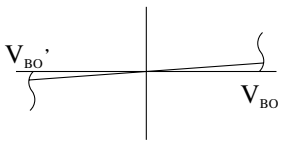
■ Electrical Characteristics $T_a = 25°C \pm 3°C$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Breakover voltage *1	V_{BO}	$I = I_{BO}$	28		36	V
Output voltage *1	V_O		4.0	7.0		V
Breakover current	I_{BO}	$V = V_{BO}$			50	µA
Temperature coefficient of breakover voltage	T.C.(V_{BO})			0.1		%/°C
Breakover voltage deviation *2	ΔV_{BO}				3.5	V

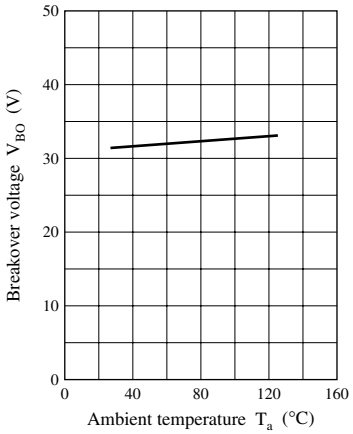
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
2. Absolute frequency of input and output is 100 MHz.
3. ∗1: Measurement of V_{BO} and V_O



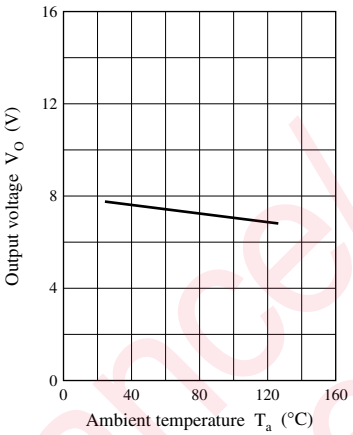
∗2: Symmetry of V_{BO}



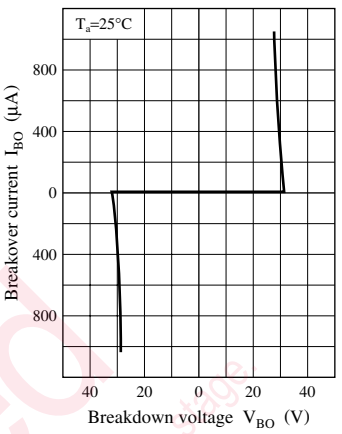
V_{BO} — T_a



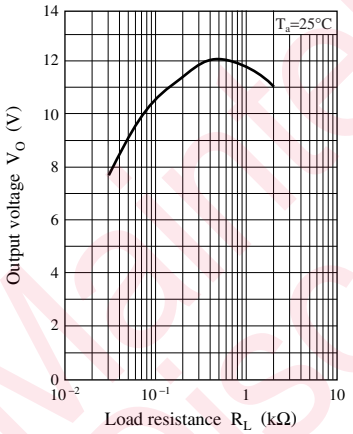
V_O — T_a



I_{BO} — V_{BO}



V_O — R_L



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